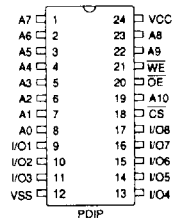# •ИYUNDAI

HY6116A Series
2K x 8-bit CMOS SRAM

DESCRIPTION

The HY6116A is a high-speed, low power and 2,048 x 8-bits CMOS static RAM fabricated using Hyundai's high performance twin tub CMOS process technology. This high reliability process coupled with innovative circuit design techniques, yields maximum access time of 85ns. The HY6116A has a data retention mode that guarantees data to remain valid at a minimum power supply voltage of 2.0 volt. Using CMOS technology, supply voltages from 2.0 to 5.5 volt have little effect on supply current in data retention mode. Reducing the supply voltage to minimize current drain is unnecessary with the HY6116A Series.

FEATURES

- **High speed-85/100/120/150ns (max.)**
- **Low power consumption**
  - **Operating : 150 mW (typ.)**
  - **Standby (CMOS) : 0.5 µW (typ.)**
- **Single 5V± 10% power supply**
- **Battery backup (L-part)**
  - **2.0V (min.) data retention**
- **Fully static operation**
  - **No clock or refresh required**
- **TTL compatible inputs and outputs**
- **Tri-state output**
- **Standard pin configuration**
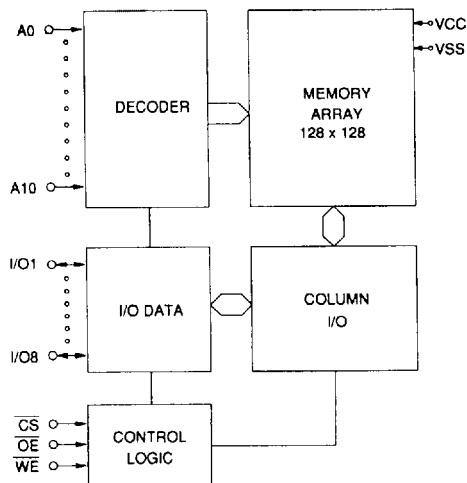 - **24 pin 600 mil PDIP**

PIN CONNECTION

A7	1	24	VCC
A6	2	23	A8
A5	3	22	A9
A4	4	21	$\overline{WE}$
A3	5	20	$\overline{OE}$
A2	6	19	A10
A1	7	18	$\overline{CS}$
A0	8	17	I/O8
I/O1	9	16	I/O7
I/O2	10	15	I/O6
I/O3	11	14	I/O5
VSS	12	13	I/O4

PDIP

PIN DESCRIPTION

Pin Name	Pin Function
$\overline{CS}$	Chip Select
$\overline{WE}$	Write Enable
$\overline{OE}$	Output Enable
A0-A10	Address Inputs
I/O1-I/O8	Data Input/Output
VCC	Power (+ 5V)
VSS	Ground

BLOCK DIAGRAM

7

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ABSOLUTE MAXIMUM RATINGS[1]

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}, V_{IN}, V_{OUT}	Power Supply, Input/Output Voltage	– 0.5 to 7.0	V
T_A	Operating Temperature	0 to 70	˚C
T_{BIAS}	Temperature under Bias	– 10 to 125	˚C
T_{STG}	Storage Temperature	– 65 to 150	˚C
P_D	Power Dissipation	1.0	W
I_{OUT}	Data Output Current	50	mA
T_{SOLDER}	Lead Soldering Temperature & Time	260•10	˚C•sec

Note :
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational of this specification is not implied. Exposure to absolute maximum rating conditions for extended period may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(T_A= 0˚C to 70˚C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{CC}	Power Supply Voltage	4.5	5.0	5.5	V
V_{IH}	Input High Voltage	2.2	-	VCC + 0.5	V
V_{IL}	Input Low Voltage	–0.5[1]	-	0.8	V

Note :
1. V_{IL} = –3.0V for pulse width less than 50ns.

TRUTH TABLE

MODE	I/O OPERATION	$\overline{CS}$	$\overline{WE}$	$\overline{OE}$
Standby	High-Z	H	X	X
Output Disabled	High-Z	L	H	H
Read	Data Out	L	H	L
Write	Data In	L	L	X

Note :
1. H= V_{IH}, L= V_{IL}, X= Don't Care

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DC CHARACTERISTICS

(TA= 0˚C to 70˚C, VCC= 5V ± 10%, unless otherwise specified.)

SYMBOL	PARAMETER	TEST CONDITIONS	POWER	MIN.	TYP.	MAX.	UNIT
I_{LI}	Input Leakage Current	$V_{SS} \leq V_{IN} \leq V_{CC}$		-2	-	2	μA
I_{LO}	Output Leakage Current	$V_{SS} \leq V_{OUT} \leq V_{CC}$ $\overline{CS}$ = V_{IH} or $\overline{OE}$= V_{IH} or $\overline{WE}$= V_{IL}		-2	-	2	μA
I_{CC1}	Average Operating Current	$\overline{CS}$ = V_{IL} Min. Duty Cycle= 100%, $I_{I/O}$= 0mA		-	30	60	mA
I_{SB}	TTL Standby Current (TTL Inputs)	$\overline{CS}$= V_{IH}		-	0.5	3	mA
I_{SB1}	CMOS Standby Current (CMOS Inputs)	$\overline{CS} \geq V_{CC}$ −0.2V		-	4	50	μA
			L	-	0.1	5	μA
V_{OL}	Output Low Voltage	I_{OL}= 2.1mA		-	-	0.4	V
V_{OH}	Output High Voltage	I_{OH}= − 1.0mA		2.4	-	-	V

Note :
1. Typical values are at VCC= 5.0V, TA= 25˚C.

AC CHARACTERISTICS

(TA= 0˚C to 70˚C, VCC= 5V ± 10%, unless otherwise noted.)

#	SYMBOL	PARAMETER	-85		-10		-12		-15		UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
	READ CYCLE										
1	tRC	Read Cycle Time	85	-	100	-	120	-	150	-	ns
2	tAA	Address Access Time	-	85	-	100	-	120	-	150	ns
3	tACS	Chip Select Access Time	-	85	-	100	-	120	-	150	ns
4	tOE	Output Enable to Output Valid	-	45	-	50	-	55	-	60	ns
5	tCLZ	Chip Select to Low-Z Output	10	-	10	-	10	-	10	-	ns
6	tOLZ	Output Enable to Low-Z Output	10	-	10	-	10	-	10	-	ns
7	tCHZ	Chip Disable to High-Z Output	0	40	0	40	0	40	0	50	ns
8	tOHZ	Output Disable to High-Z Output	0	40	0	40	0	40	0	50	ns
9	tOH	Output Hold from Address Change	10	-	10	-	10	-	15	-	ns
	WRITE CYCLE										
10	tWC	Write Cycle Time	85	-	100	-	120	-	150	-	ns
11	tCW	Chip Select to End of Write	60	-	65	-	70	-	90	-	ns
12	tAW	Address Valid to End of Write	70	-	80	-	105	-	120	-	ns
13	tAS	Address Set-up Time	0	-	0	-	0	-	0	-	ns
14	tWP	Write Pulse Width	55	-	60	-	70	-	80	-	ns
15	tWR	Write Recovery Time	0	-	0	-	0	-	0	-	ns
16	tWHZ	Write to High-Z Output	0	30	0	30	0	35	0	40	ns
17	tDW	Data to Write Time Overlap	30	-	30	-	35	-	40	-	ns
18	tDH	Data Hold from Write Time	0	-	0	-	0	-	0	-	ns
19	tOW	Output Active from End of Write	10	-	10	-	10	-	10	-	ns

AC TEST CONDITIONS

(TA= 0˚C to 70˚C, VCC= 5V ±10%, unless otherwise specified.)

PARAMETER	VALUE
Input Pulse Level	0.8V to 2.4V
Input Rise and Fall Time	5ns
Input and Output Timing Reference Levels	1.5V
Output Load	C_L= 100pF + 1TTL Load

AC TEST LOADS
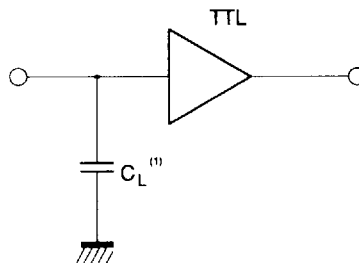
Note :
1.Including jig and scope capacitance.
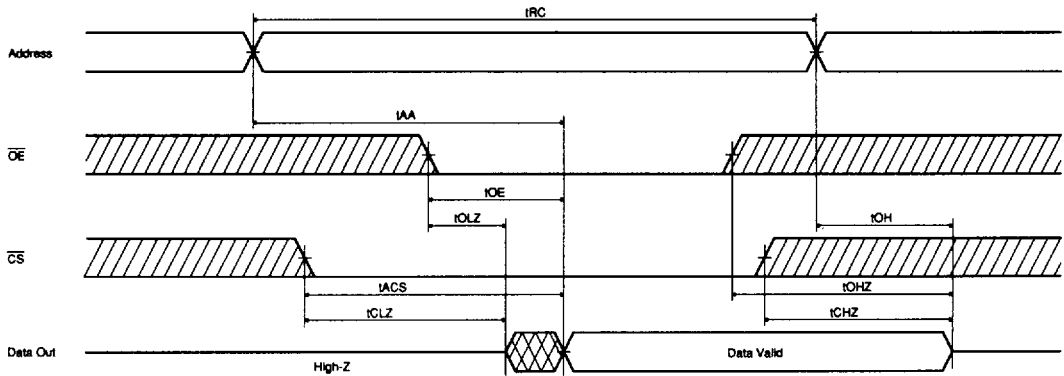
CAPACITANCE

(TA= 25˚C, f= 1MHz)

SYMBOL	PARAMETER	CONDITION	MAX.	UNIT
C_{IN}	Input Capacitance	V_{IN}= 0V	6	pF
$C_{I/O}$	Input/Output Capacitance	$V_{I/O}$= 0V	8	pF

Note :
1. This parameter is sampled and not 100% tested.
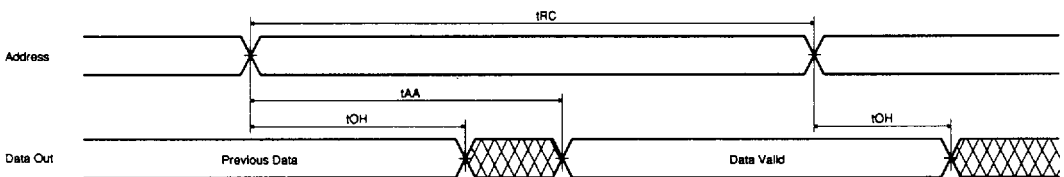
TIMING DIAGRAM

READ CYCLE 1

Note (READ CYCLE):
1. t_{CHZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, t_{CHZ} max. is less than t_{CLZ} min. both for a given device and from device to device.
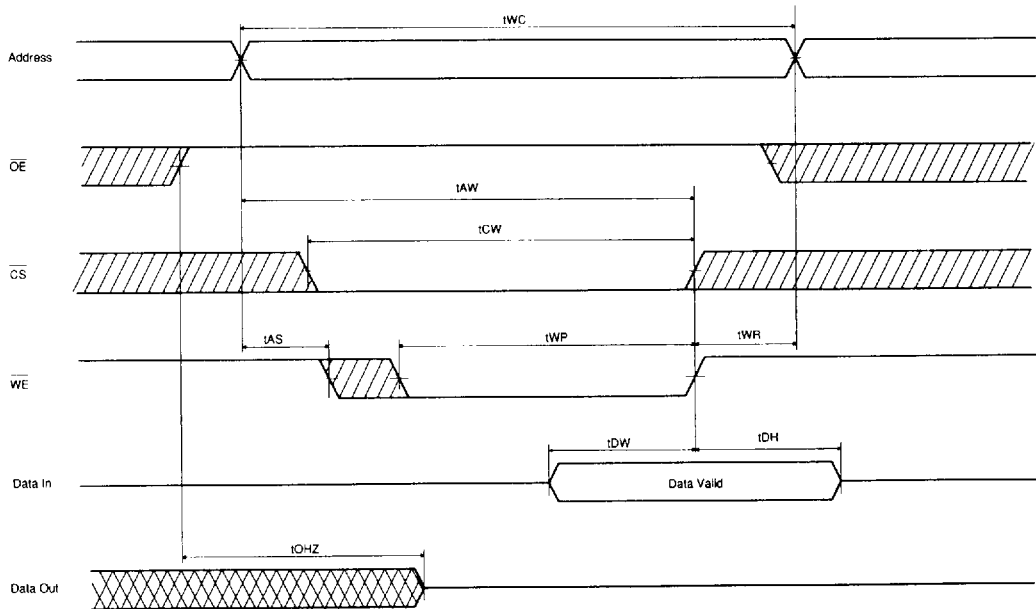3. $\overline{WE}$ is high for read cycle.

READ CYCLE 2

Note(READ CYCLE):
1. $\overline{WE}$ is high for read cycle.
2. Device is continuously selected $\overline{CS}= V_{IL}$.
3. $\overline{OE}= V_{IL}$.

WRITE CYCLE 1 ($\overline{OE}$ Clocked)

WRITE CYCLE 2 ($\overline{OE}$ Low Fixed)
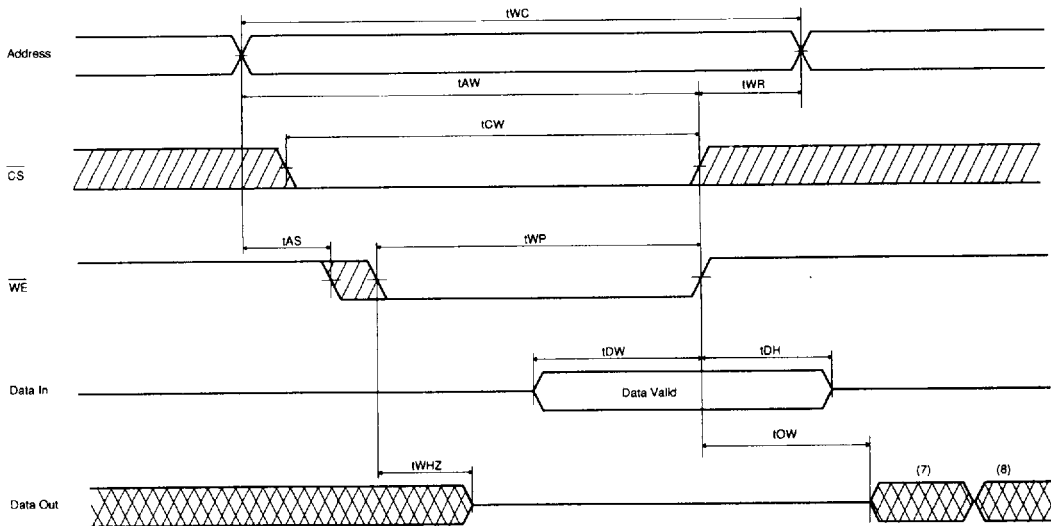
Note (WRITE CYCLE):

1. A write occurs during the ovelap of a low $\overline{CS}$ and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS}$ going low, and $\overline{WE}$ going low: A write ends at the earlist transition among $\overline{CS}$ going high and $\overline{WE}$ going high. t_{WP} is measured from the beginning of write to the end of write.
2. t_{CW} is measured from the later of $\overline{CS}$ going low to end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as $\overline{CS}$ or $\overline{WE}$ going high.
5. If $\overline{OE}$ and $\overline{WE}$ are in the read mode during this period, the I/O pins are in the output low-Z state, inputs of opposite phase of the output must not be applied because bus contention can occur.
6. If $\overline{CS}$ goes low simultaneously with $\overline{WE}$ going low or after $\overline{WE}$ going low, the outputs remain in high impedance state.
7. D_{OUT} is the same phase of lastest written data in this write cycle.
8. D_{OUT} is the read data of the new address.
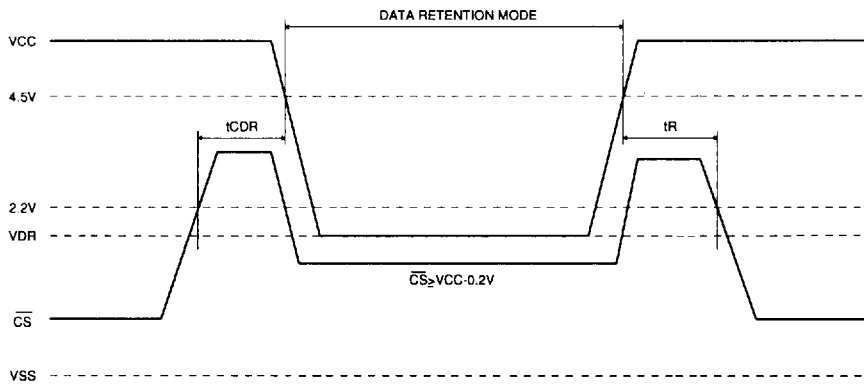
DATA RETENTION CHARACTERISTICS

(T$_A$= 0˚C to 70˚C)

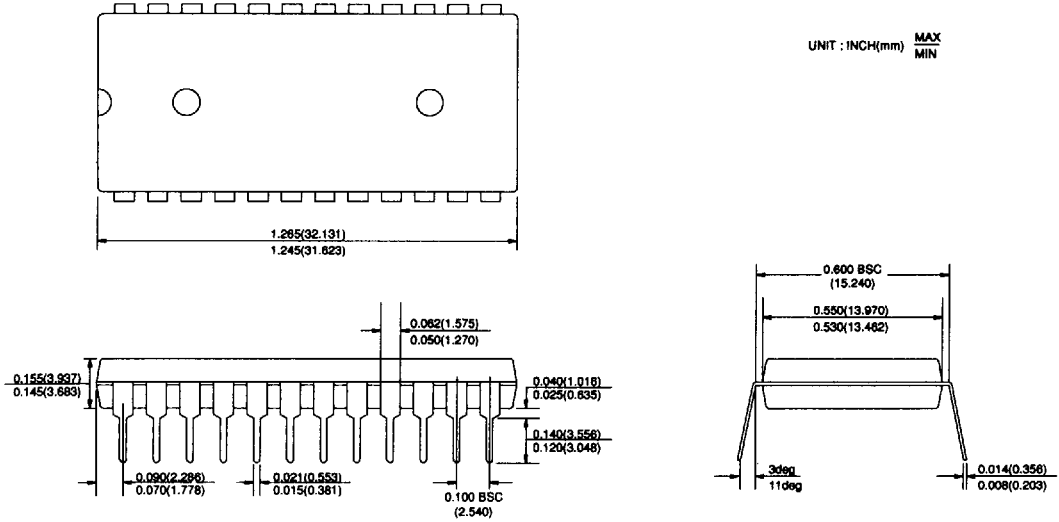| SYMBOL	PARAMETER	TEST CONDITION	POWER	MIN.	TYP.	MAX.	UNIT
V$_{DR}$	V$_{CC}$ for Data Retention	$\overline{CS} \geq$ V$_{CC}$–0.2V V$_{SS}\leq$ V$_{IN}\leq$ V$_{CC}$		2.0	-	-	V
I$_{CCDR}$	Data Retention Current	V$_{CC}$= 3.0V $\overline{CS} \geq$ V$_{CC}$–0.2V, V$_{SS} \leq$ V$_{IN} \leq$ V$_{CC}$	L	-	0.05	2	μA
t$_{CDR}$	Chip Disable to Data Retention Time	See Data Retention Timing Diagram		0	-	-	ns
t$_R$	Operating Recovery Time			t$_{RC}$[2]	-	-	ns

Notes :
1. Typical values are at the condition of T$_A$= 25˚C.
2. t$_{RC}$ is read cycle time.

DATA RETENTION TIMING DIAGRAM 1

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PACKAGE INFORMATION

600 mil 24 pin Dual In-line Package (P)

UNIT : INCH(mm) $\frac{MAX}{MIN}$

1.265(32.131)
1.245(31.623)

0.062(1.575)
0.050(1.270)

0.155(3.937)
0.145(3.683)

0.040(1.016)
0.025(0.635)

0.140(3.556)
0.120(3.048)

0.090(2.286)
0.070(1.778)

0.021(0.553)
0.015(0.381)

0.100 BSC
(2.540)

0.600 BSC
(15.240)

0.550(13.970)
0.530(13.462)

3deg
11deg

0.014(0.356)
0.008(0.203)

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ORDERING INFORMATION

PART N0.	SPEED	POWER	PACKAGE
HY6116AP	85/100/120/150		PDIP
HY6116ALP	85/100/120/150	L-part	PDIP

4675088 0003619 975